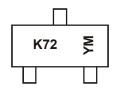


Marking Information



K72 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: I = 2021) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Year	2002		2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	N			J	K	L	М	N	0	Р	R	S
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	60	V
Drain-Gate Voltage R _{GS} ≤ 1.0MΩ			V_{DGR}	60	V
Gate-Source Voltage		Continuous Pulsed (Note 8)	V_{GSS}	±20 ±40	V
Continuous Drain Current (Note 5) V _{GS} = 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$ $T_A = +100^{\circ}C$	Ι _D	170 120 105	mA
Continuous Drain Current (Note 6) V _{GS} = 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$ $T_A = +100^{\circ}C$	Ι _D	210 150 135	mA
Maximum Continuous Body Diode Forward Current (No	Is	0.2 0.5	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	800	mA

Thermal Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Total Power Dissipation	(Note 5)	כ	370	mW	
Total Fower Dissipation	(Note 6)	P_{D}	540	IIIVV	
Thermal Resistance, Junction to Ambient	(Note 5)	ם	348		
Thermal Resistance, Junction to Ambient	(Note 6)	$R_{\theta JA}$	241	°C/W	
Thermal Resistance, Junction to Case	(Note 6)	R ₀ JC	91		
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C	

Notes:

- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.



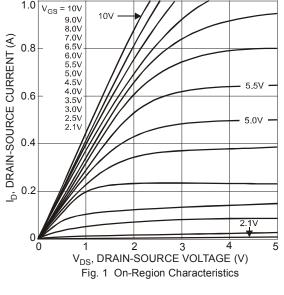
Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

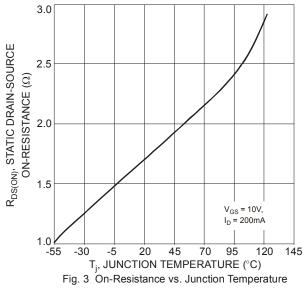
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)		•					
Drain-Source Breakdown Voltage		BV _{DSS}	60	70	_	V	$V_{GS} = 0V, I_D = 10\mu A$
Zero Gate Voltage Drain Current	@ T _J = +25°C @ T _J = +125°C	I _{DSS}	_	_	1.0 500	μΑ	V _{DS} = 60V, V _{GS} = 0V
Gate-Body Leakage	I _{GSS}	_	_	±10	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage		$V_{GS(th)}$	1.0	_	2.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance	@ T _J = +25°C @ T _J = +25°C	R _{DS(on)}	_	3.2 2.4	7.5 5.0	Ω	$V_{GS} = 5.0V, I_D = 0.05A$ $V_{GS} = 10V, I_D = 0.5A$
	@ T _J = +125°C	20(0.1)		4.4	13.5		$V_{GS} = 10V, I_D = 0.5A$
On-State Drain Current	1	I _{D(on)}	0.5	1.0	_	Α	V _{GS} = 10V, V _{DS} = 7.5V
Forward Transconductance		g FS	80	_	_	mS	V _{DS} =10V, I _D = 0.2A
Diode Forward Voltage		V _{SD}	_	0.78	1.5	V	V _{GS} = 0V, I _S = 115mA
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance		C _{iss}	_	22	50	pF	.,
Output Capacitance		Coss	_	11	25	pF	V _{DS} = 25V, V _{GS} = 0V f = 1.0MHz
Reverse Transfer Capacitance		C _{rss}	_	2.0	5.0	pF	1.0141112
Gate Resistance		R_g	_	120	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, f = 1.0MHz
Total Gate Charge (V _{GS} = 4.5V)		Q_g	_	223	_		
Gate-Source Charge		Qgs	_	82	_	рC	V_{DS} = 10V, I_{D} = 250mA
Gate-Drain Charge		Q_{gd}	_	178	_		
Turn-On Delay Time		t _{D(on)}	_	2.8	_		
Turn-On Rise Time		t _R	_	3.0		no	$V_{DD} = 30V, I_D = 0.2A,$
Turn-Off Delay Time	Turn-Off Delay Time			7.6		ns	R_L = 150 Ω , V_{GEN} = 10 V , R_{GEN} = 25 Ω
Turn-Off Fall Time		t _F	_	5.6	_		- OLIV 2011

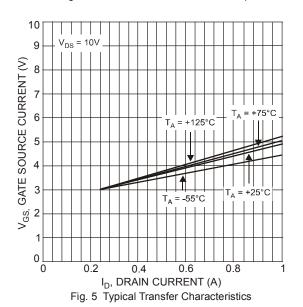
Notes:

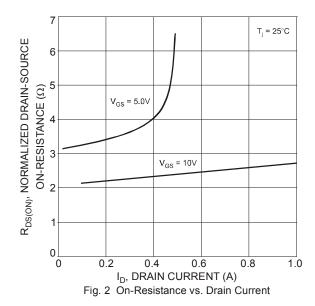
^{7.} Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.

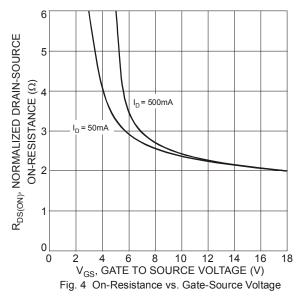












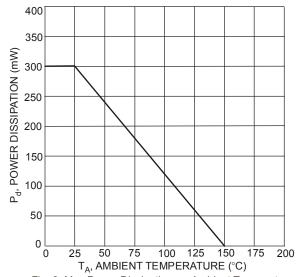


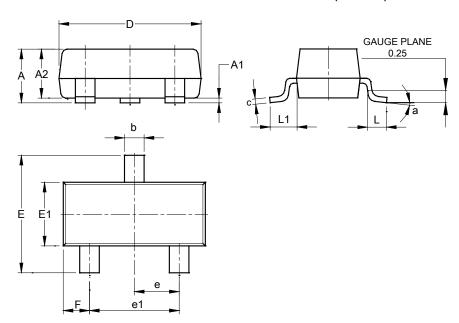
Fig. 6 Max Power Dissipation vs. Ambient Temperature



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23 (Standard)

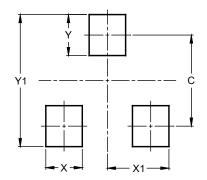


SOT23 (Standard)							
Dim	Min	Max	Тур				
Α	0.90	1.15	1.025				
A1	0.00	0.10	0.05				
A2	0.85	1.10	0.975				
b	0.30	0.51	0.40				
С	0.080	0.202	0.11				
D	2.80	3.00	2.90				
Е	2.25	2.55	2.40				
E1	1.20	1.40	1.30				
е	0.89	1.03	0.915				
e1	1.78	2.05	1.83				
F	0.40	0.60	0.535				
L1	0.45	0.61	0.55				
L	0.25	0.55	0.40				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23 (Standard)



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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